

1.ELECTRICAL CHARACTERISTICS:

This filter satisfies Table 1 at Temperature Range : -30 to +85°C

CENTER FREQUENCY :fo= 2450 MHz

PASSBAND WIDTH :fo ±50 MHz

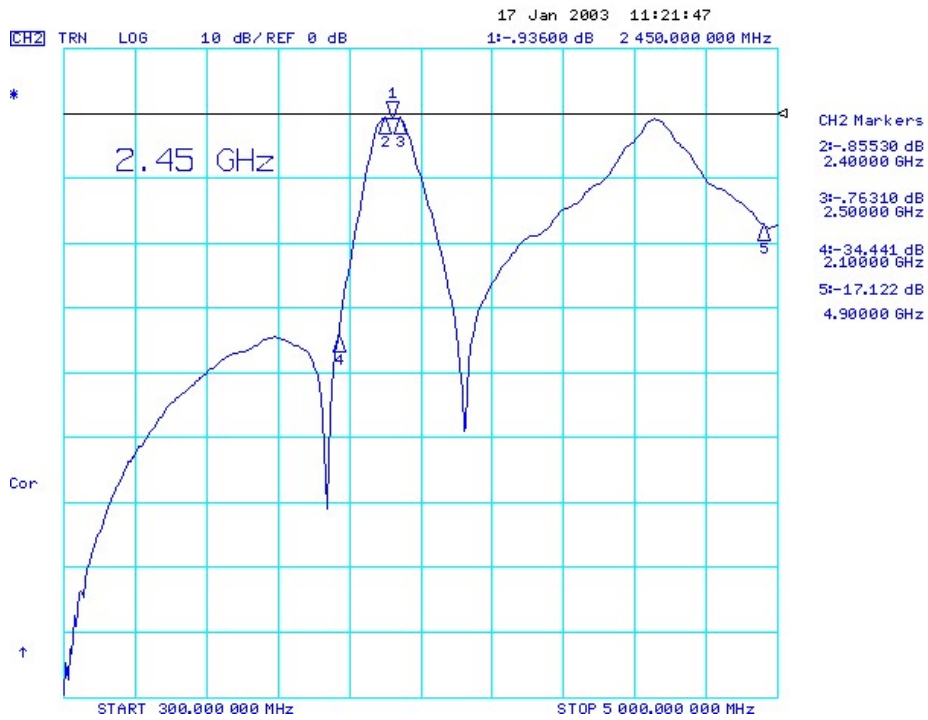
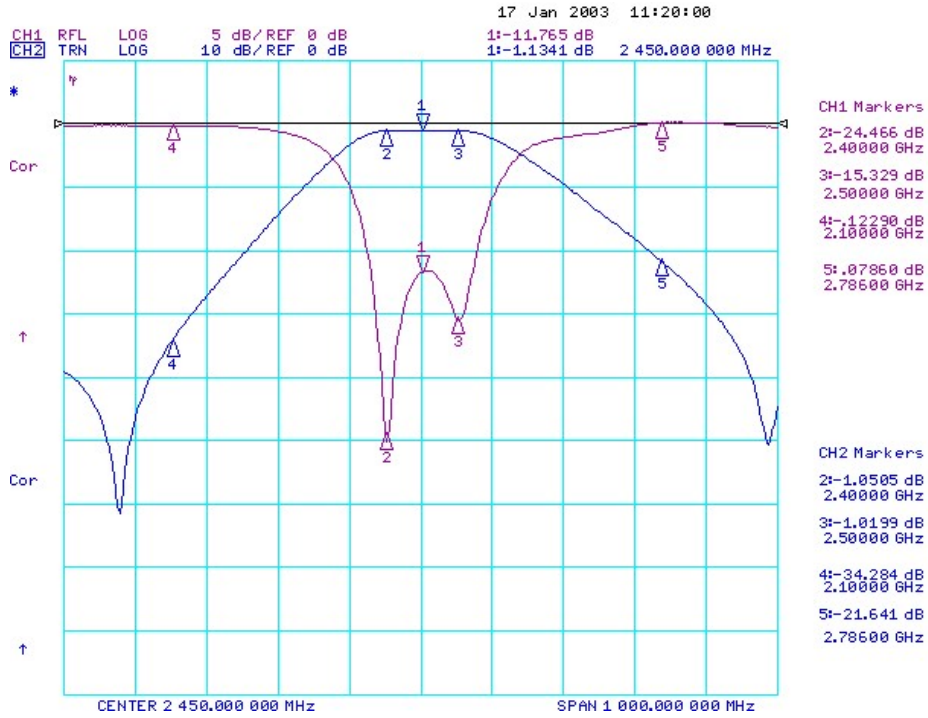
INPUT/OUTPUT IMPEDANCE :50Ω

Max. INPUT POWER : 1 W

TABLE 1

NO.	ITEM	SPECIFICATION	
1	PASS BAND INSERTION LOSS	1.3 dB max	
2	PASS BAND RIPPLE	0.8 dB max	
3	PASS BAND RETURN LOSS	9.6 dB min	
4	STOP—BAND ATTENUATION	at 2033~2098MHz	20 dB min
		at 2100 MHz	30 dB min
		at 2786 MHz	18 dB min
		at 4900 MHz	12 dB min

TYPICAL ELECTRICAL CHARACTERISTICS



2. MANUFACTURING CONSIDERATIONS:

2-1 COMPONENT HANDLING:

All necessary special handling techniques shall be adopted in order to avoid contamination of metallization/terminations. Examples include use of finger cots, plastic tweezers, etc.

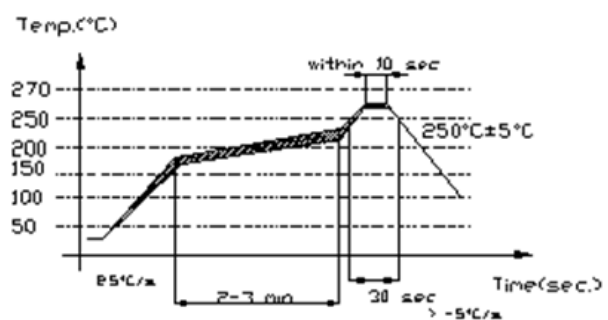
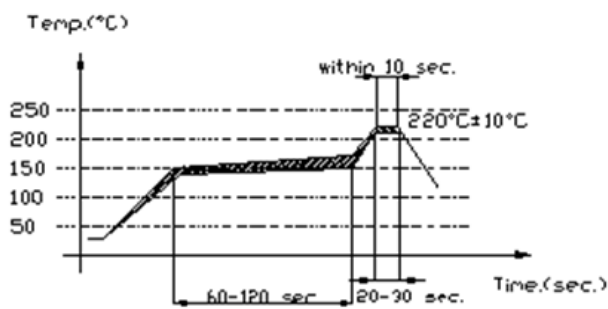
2-2 PART PLACEMENT:

A placement force of up to 200 grams is applied (using a 2.0 mm or a 0.080 inch diameter rod) to the center of the part while it remaining in its carrier tape.

2-3 REFLOW SOLDERING CONDITION:

The recommended reflow soldering condition is shown in following figure. The temperature should be the temperature at the device.

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type (measuring point on top surface of the component)	reflow 230 (max. 10 sec.)	reflow 260 (max. 10 sec.)	°C
Composition of solder paste	62Sn/36Pb/2Ag	96.5Sn/3Ag/0.5CuI	



2-4 SOLDERING WITH IRON:

Soldering condition : Soldering iron temperature 270 ± 10 °C.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds.

2-5 STORAGE CONDITIONS:

2-5-1 Use the product of former delivery first.

2-5-2 Temperature: 0°C to 40 °C

Humidity: 80%RH or less

2-5-3 The product should not be stored exceeding six months (as packed by the manufacturer) or one month (once unpacked). Use the product within that period.

